

Nickel Barrier

Multilayer Ceramic Capacitors



Features:

- Multilayer ceramic chip capacitor.
- Nickel barrier termination.
- High performance and reliability.
- 0603, 0805, and 1206 case size.

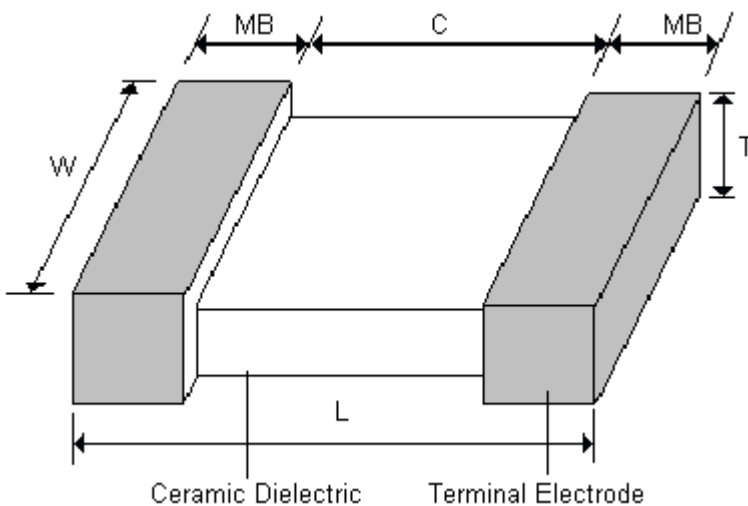


Rated Voltage

Code	Rated Voltage
A	100
B	16
T	25
U	50

Part Dimension

Dimensions						
Length (L)	Width (W)	Maximum Thickness (T)	Minimum MB	Minimum G	Voltage (V)	Type
1.6 ±0.1	0.8 ±0.1		0.20	0.40	6.3 ~ 50	0603
2.0 ±0.2	1.25 ±0.1	1.40	0.25	0.70	6.3 ~ 500	0805
3.2 ±0.2	1.60 ±0.2	1.52		1.40	6.3 ~ 1000	1206



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Temperature Characteristics Code

Code	Temperature Coefficient	Operation Temperature (°C)	Capacitance Change
C	NPO (Class I)	-55°C ~ +125	0 ±30ppm/°C
R	X7R (Class II)		±15%
F	Y5V (Class II)	30°C ~ +85	+22% ~ -82%

Capacitance Code

Code	Capacitance (pF)
010	1*
1R5	1.5
100	10*
101	100*
102	1000*
103	10000*
222	2200*
472	4700*

Tolerance Code

Code	Tolerance (%)
J	±5
K	±10
Z	+80/-20

PS:

- * -- Two significant digits followed by number of zeros.
- Temperature coefficient (T.C.) vs. Proper tolerance applied:
 - NPO: For all tolerance
 - X7R+X5R: K+M Tolerance
 - Y5V+Z5U: M+Z Tolerance

Termination Code

Code	N
Termination Type	Nickel

Packaging Code

Code	B	T
Packaging Type	Bulk	Tape and Reel

Standard Test Conditions

Tests shall, unless otherwise specified, be carried out at 15 to 35°C and RH 45 to 75%. If any doubt and argument has been encountered in judgement, the final test shall be done at 25 ±2°C, RH45 to 55% and 860 ~ 1060mbar. (Based on JIS standard).

Disposition

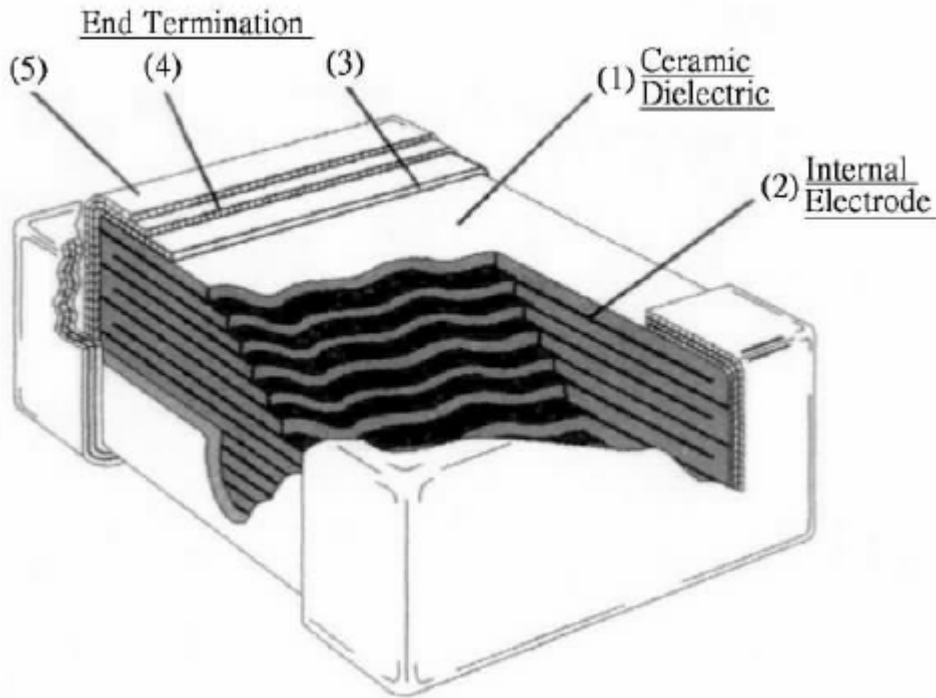
If question to the measuring result in judgement, take the capacitor under a specified temperature for 30 minutes at least before measurement.



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Structure



Ag/Pd Series

Number	Specifications	Material	Minimum Termination Plating Thickness (μm)
1	Ceramic Dielectric	Ceramic	
2	Internal Electrode	Ag-Pd	
3	End Terminal	Ag layer	40
4		Ni layer	1.5 - 3.5
5		Sn-Pb layer or Sn layer	3 - 8

BME Series

Number	Specifications	Material	Minimum Termination Plating Thickness (μm)
1	Ceramic Dielectric	Ceramic	
2	Internal Electrode	Ni	
3	End Termination	Cu layer	40
4		Ni layer	1.5 - 3.5
5		Sn-Pb layer or Sn layer	3 - 8

Storing Condition And Term

Recommends the storing of products within 6 months at temperature 15 ~ 35°C and humidity 70%RH maximum. If the product stored over 6 months, please reconfirm its solderability before use.

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Performance

Item	Performance	Test or Inspection Method																							
External Appearance	No defects which may affect performance	Visual inspection and dimension measurement																							
Voltage Proof	Withstand test voltage without insulation breakdown or other damage	<p>DC Tested voltage shall be applied for 1 ~ 5 second. Charge/discharge current shall not exceed 50mA (PS : Ra - Rated Voltage)</p> <table border="1"> <thead> <tr> <th rowspan="2">Code</th> <th colspan="3">Temperature Coefficient</th> </tr> <tr> <th>NPO</th> <th>X7R/X5R</th> <th>Y5V</th> </tr> </thead> <tbody> <tr> <td>≤200V</td> <td colspan="3">2.5Ra</td> </tr> <tr> <td>250V</td> <td colspan="3">2.0Ra</td> </tr> <tr> <td>500V/630V</td> <td colspan="3">1.5Ra</td> </tr> <tr> <td>≥1KV</td> <td>1.5Ra</td> <td>1.25Ra</td> <td>-</td> </tr> </tbody> </table>	Code	Temperature Coefficient			NPO	X7R/X5R	Y5V	≤200V	2.5Ra			250V	2.0Ra			500V/630V	1.5Ra			≥1KV	1.5Ra	1.25Ra	-
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Insulation Resistance	<p>NPO: 100,000MΩ minimum or R x C ≥ 1000Ω x F (Which ever is smaller)</p> <p>X7R, X5R, Y5V, Z5U: 10,000MΩ minimum or R x C ≥ 1000Ω x F (Which ever is smaller)</p>	<table border="1"> <thead> <tr> <th>Rated Voltage</th> <th>DC Tested Voltage</th> </tr> </thead> <tbody> <tr> <td><1KV</td> <td>1.0 Ra</td> </tr> <tr> <td>≥1KV</td> <td>1KV</td> </tr> </tbody> </table> <p>Apply DC tested voltage for 60 ±5 minute. (PS : Ra - Rated Voltage)</p>	Rated Voltage	DC Tested Voltage	<1KV	1.0 Ra	≥1KV	1KV																	
Rated Voltage	DC Tested Voltage																								
<1KV	1.0 Ra																								
≥1KV	1KV																								
Capacitance (Cap.)	Within the specified tolerance																								
Dissipation Factor (D.F)	<p>NPO: ≥30pF: Q ≥ 1000 <30pF: Q ≥ 400 + 20C</p> <p>PS:C: Nominal Capacitance (pF) X7R, X5R, Y5V, and Z5U : (Maximum Value)</p> <table border="1"> <thead> <tr> <th>T.C.</th> <th>≥ 50V</th> <th>25V</th> <th>16V</th> <th>≤10V</th> </tr> </thead> <tbody> <tr> <td>X7R/ X5R</td> <td>2.5%</td> <td>3.0%</td> <td>3.5%</td> <td>5.0%</td> </tr> <tr> <td>Z5U</td> <td>4.0%</td> <td>-</td> <td>-</td> <td>-</td> </tr> <tr> <td>Y5V</td> <td>5.0%</td> <td>7.5%</td> <td>9.0%</td> <td>12.5%</td> </tr> </tbody> </table>	T.C.	≥ 50V	25V	16V	≤10V	X7R/ X5R	2.5%	3.0%	3.5%	5.0%	Z5U	4.0%	-	-	-	Y5V	5.0%	7.5%	9.0%	12.5%	<p>Measuring Frequency: Z5U, Y5V, X7R, X5R : 1KHz ±50Hz NPO: >1000pF: 1KHz ±50Hz. ≤1000pF: 1MHz 100KHz.</p> <p>Measuring Voltage: Z5U: 0.5V_{rms}.</p> <p>NPO: X7R, X5R, Y5V: 1.0 ±0.2V_{rms}.</p>			
T.C.	≥ 50V	25V	16V	≤10V																					
X7R/ X5R	2.5%	3.0%	3.5%	5.0%																					
Z5U	4.0%	-	-	-																					
Y5V	5.0%	7.5%	9.0%	12.5%																					

Item		Performance				Test or Inspection Method		
Temperature Characteristic of Capacitance	Temperatures Coefficient					The temperature coefficient is determined using the capacitance measured in step 3 as a reference. Test the specimen from step 1 through step 5, the capacitance shall be within the specified tolerance for the capacitance coefficient and capacitance change as left table.		
	TC	Operating Temperature	Capacitance Change (DC)					
	NPO	-55 ~ +125°C	0 ±30 (ppm/°C)					
	X7R	-55 ~ +125°C	±15%					
	X5R	-55 ~ +85°C	±15%					
	Y5V	-55 ~ +125°C	+22% ~ -82%					
	Z5U	-55 ~ +125°C	+22% ~ -56%					
Solderability		New solder to over 95% of termination				Completely soak both terminal electrodes in solder at specified temperature for 3 ±0.5 second a. For Tin-Lead (Sn/Pb) Termination product: 235 ±5°C. b. For Lead-free (Pure Sn) Termination product: 245 ±5°C.		
Leaching						Completely soak both terminal electrodes in solder at 270 ±5°C for 40 ±1second.		
Soldering to heat	External Appearance	No mechanical Damage					Completely immerse both terminations in solder at 270 ±5°C for 10 ±3 second. Leave the capacitors in ambient condition for 2 4 ±2 hours before measurement. *Preconditioning: F(only for Class 2): Perform a heat treatment at 150 +0-10°C for one hour and then let sit for 24 ±2 hours at room temperature. Perform the initial measurement.	
	Capacitance Change (Δ C/C)	NPO	±2.5% or ±0.25 pF maximum (Whichever is larger)					
		X7R/X5R	±7.5%					
		Z5U	±20%					
		Y5V	±20%					
DF	NPO: C ≥30pF : Q ≥ 1000 C<30pF:Q ≥ 400 + 20°C PS: C : Nominal Capacitance (pF) X7R, X5R, Y5V, Z5U : (Maximum Value)							
	T.C.	≥ 50V	25V	16V	≤10V			
	X7R/X5R	2.5%	3.0%	3.5%	5.0%			
	Z5U	4.0%	-	-	-			
Y5V	5.0%	7.5%	9.0%	12.5%				
IR		NPO: 100,000MW minimum or R x C ≥1000W x F (Whichever is smaller) X7R, X5R, Y5V, Z5U: 10,000MW minimum or R x C ≥1000W x F (Whichever is smaller)						

Item		Performance	Test or Inspection Method
Humidity (Steady State) and Humidity Load	External Appearance	No mechanical damage	Humidity load: (Not apply for the product with rated voltage $\geq 250V$): Apply the rated voltage at temperature $40 \pm 2^\circ C$ and humidity 90 to 95%RH for 1000+48/-0 hours. Leave the capacitors in ambient condition for the following time before measurement. Class 1: 1~2 hours. Class 2: 24 ± 2 hours. Charge / discharge current shall not exceed 50 mA. Preconditioning: (only for class 2): Apply the rated DC voltage for 1hour at $40 \pm 2^\circ C$. Remove and let sit for 48 ± 4 hours at room temperature. Perform initial measurement. Humidity (steady state): The test procedure is same as that in Humidity load but only without rated voltage applied.
	Capacitance Change ($\Delta C/C$)	NPO: $\pm 5\%$ or ± 0.5 pF maximum (Whichever is larger) X7R/X5R: $\pm 12.5\%$ Y5V: $\pm 30\%$ Z5U: $\pm 30\%$	
	DF	NPO: $C \geq 30pF$: $Q \geq 350$ $10pF \leq C < 30pF$: $Q \geq 100 + 2.5^\circ C$ $C < 10pF$: $200 + 10^\circ C$ PS: C : Nominal Capacitance (pF) $C < 30pF$: $Q \geq 400 + 20^\circ C$ PS: C : Nominal capacitance (pF) X7R, X5R: Less than 2 times of initial value Y5V and Z5U: Less than 1.5 times of initial value	
	IR	500M Ω minimum or 25 Ω *F (Which ever is smaller)	
Load Life	External Appearance	No mechanical damage	Apply 2 x rated voltage at maximum operating temperature $\pm 2^\circ C$ for 1000 +48/-10 hours. Leave the capacitors in ambient condition for the following time before measurement. Class I: 1~2 hours Class II: 24 ± 2 hours Charge / discharge current shall. not exceed 50 mA. Preconditioning: (only for class 2): Apply 200% of the rated DC voltage for 1 hour at the maximum operating temperature $\pm 3^\circ C$. Remove and let sit for 24 ± 2 hours at room temperature. Perform initial measurement.
	Capacitance Change ($\Delta C/C$)	NPO: $\pm 3\%$ or ± 0.3 pF maximum (Whichever is larger) X7R/X5R: $\pm 12.5\%$ Y5V: $\pm 30\%$ Z5U: $\pm 30\%$	
	DF	NPO: $C \geq 30pF$: $Q \geq 350$ $30pF > C \geq 10pF$: $Q \geq 275 + 205^\circ C$ $C < 10pF$: $Q \geq 200 + 10^\circ C$ PS: C : Nominal capacitance (pF) X7R, X5R: Less than 2 times of initial value Y5V and Z5U : Less than 1.5 times of initial value	
	IR	1000M Ω minimum or 50 Ω *F (Whichever is smaller)	

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Precaution For Handling

The multi-layer ceramic chip capacitors, may fall in a short circuit mode or in an open-circuit mode when subjected to severe conditions of electrical, environmental and/or mechanical stress beyond the specified "Ratings" and specified "Condition" in the Catalog and the Specifications, resulting in burnout, flaming or glowing in the worst case. So some common sense of application by customer is necessary. Here the following article are some key points that need to take attention in application for customer reference only:

Operating Conditions and Circuit Design

Operating temperature range

The specified "Operating Temperature Range" in the catalog is absolute maximum and minimum temperature rating. So in any case, each the Capacitor shall be operated within the specified "Operating Temperature Range".

Design of Voltage applications

The capacitors shall not be operated exceeding the specified "Rated Voltage" in the catalog. If voltage ratings are exceeded the Capacitors could result in failure of damage. In case of application of DC and AC voltage to the capacitors, the designed peak voltage shall be within the specified "Rated Voltage".

Charging and Discharging Current

The capacitors shall not be operated beyond the specified "Maximum Charging / Discharging Current Rated" in the specification, Application to a low impedance circuit such as a "secondary power circuit" are not recommended for safety.

Temperature Rise by Dielectric Loss of the capacitor

The "Operating Temperature Range" mentioned above shall include a maximum surface temperature rise of 20°C, which is caused by the Dielectric loss of the Capacitor and applied electrical stress (such as voltage, frequency and wave form etc.)

It is recommended to measure and check "Surface temperature of the Capacitor" in your equipment at your estimated / designed maximum ambient temperature.

Restriction on Environmental Conditions

The Capacitors shall not be operated and / or stored under following environmental conditions:

- (a) To be exposed directly to water or salt water.
- (b) To be exposed directly to sunlight.
- (c) Under conditions of dew formation.
- (d) Under conditions of corrosive atmosphere such as hydrogen sulfas, sulphurous acid, chlorine, or ammonia etc.
- (e) Under severe condition of vibrations or shock beyond the specified conditions in the Specifications.

Secular change in Capacitance

(1) Peculiar characteristics of "Secular Changes in Capacitance" are observed in the Capacitors (Class 2 High Dielectric Constant Temperature Characteristics "X7R" and "Y5V". The "secular change" shall be considered in your circuit design.

(2) The Capacitance change, due to the individual characteristics of ceramic dielectric materials applied, can be recovered to the each initial values at shipping by a heat treatment (140 to 150°C for 1 hour).

Design of Printed Circuit Board

Selection of Printed Circuit Boards

When the Capacitors are mounted and soldered on an "Aluminium's Substrate has influences on Capacitor's reliability against "Temperatures Cycles" and "Heat shock" because of difference of thermal expansion dose not deterioration the characteristics of the Capacitors.

There are some thermal expansion factor for different kink of PC board material as follows

PC Board Material	Thermal Expansion Factor (mm/°C)
Glass Epoxy	1.4 x 10 ⁻⁵
Paper Phenol	2.2 x 10 ⁻⁵
Composite	
Alumina	6.5 x 10 ⁻⁶

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Design of Land Pattern

Recommended Dimensions of Lands. As shown in Table 1 and Figure 1.

Note: * Too large land required excess amount of solder.

** The Dimensions shall be symmetrical.

Figure 1 Recommended Land Dimensions:

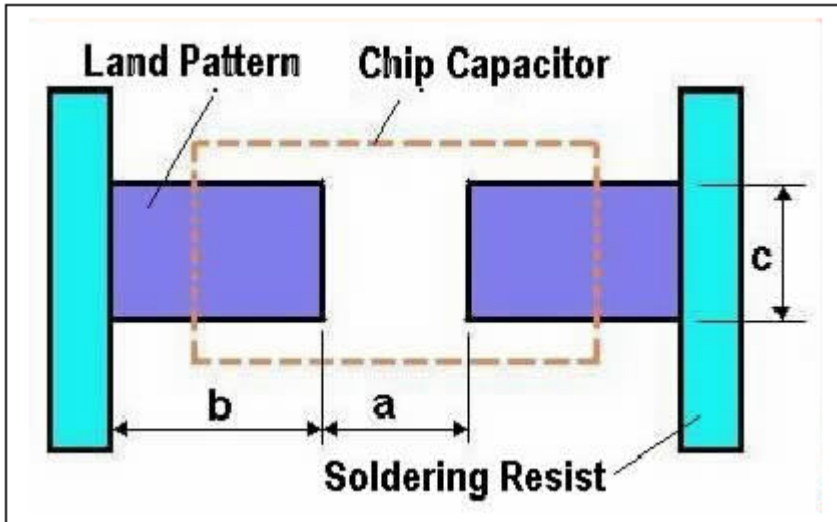


Table 1

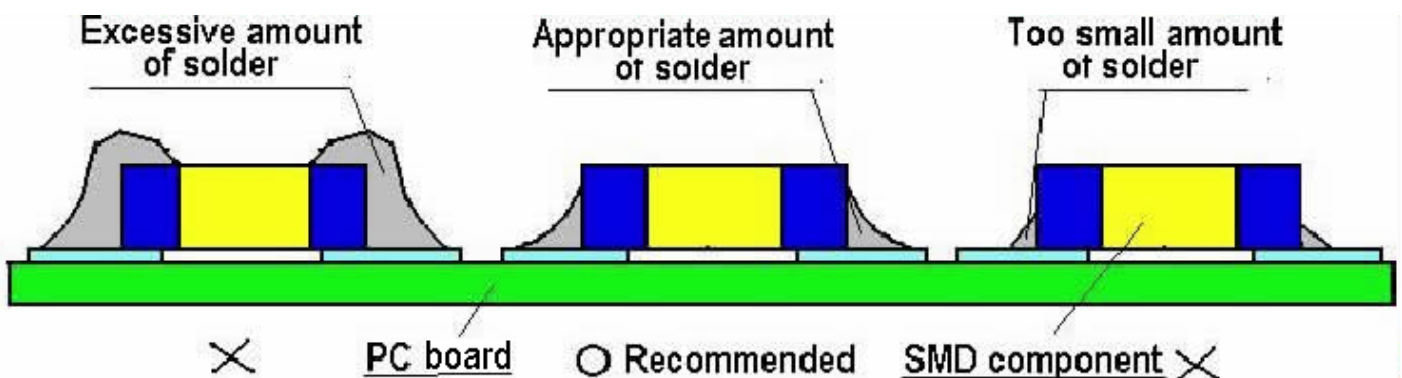
Size	Chip Dimensions		Land Dimension		
	Length (L)	Width (W)	a	b	c
0603	1.6	0.8	0.70 ~ 1.00	0.80 ~ 1.00	0.60 ~ 0.80
0805	2.0	1.25	1.00 ~ 1.30	1.00 ~ 1.20	0.80 ~ 1.10
1206	3.2	1.6	2.10 ~ 2.50	1.10 ~ 1.30	1.10 ~ 1.30

Dimensions: Millimetres

Recommend amount of solder:

Recommended amount of solder: As shown in Figure 2. Excess amount of solder gives large mechanical stresses to the capacitors / Components.

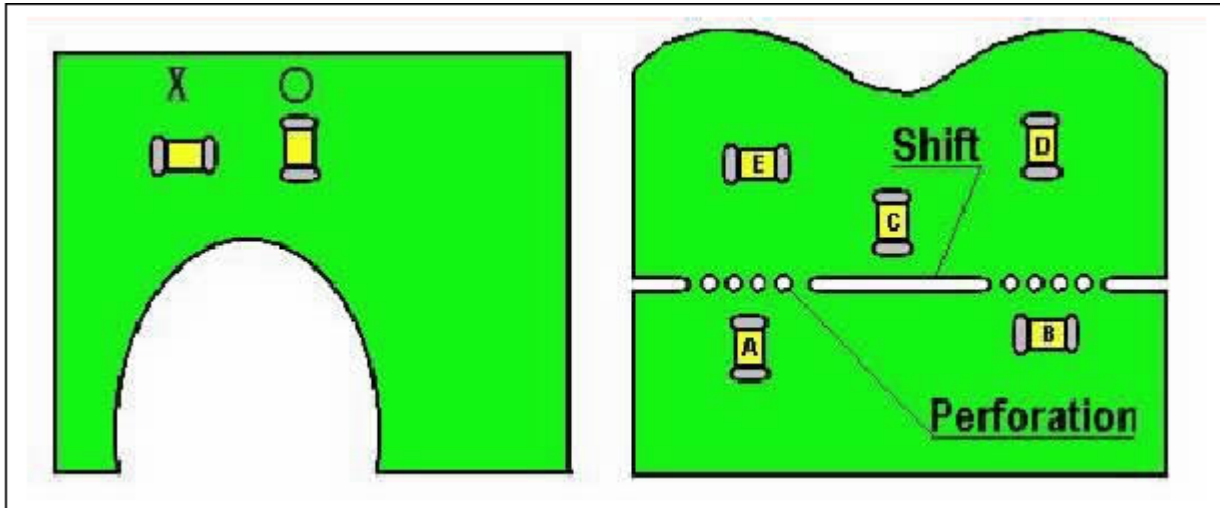
Figure 2: Recommended amount of solder



Component Layout

When placing / mounting the capacitors / components near an area which is apt to bend or a grid groove on the PC board. It is advisable to have both electrodes subjected to uniform stresses, or to position the component electrodes at right angles to the grid groove or bending line.

Figure 3 Component Layout



Uneven mounting density

O: Proper X: Improper

Probability at which the chip capacitor is broken by the stress on PC board break

$A > B = C > D > E$

Mounting Density and Spaces

Placements in too narrow spaces between components may cause "Solder Bridges" during soldering. The minimum space between components shall be 0.5mm in view of the positioning tolerances of the mounting machines and the dimensional tolerances of the components and PC boards.

Applications of Solder Resist

Application of Solder Resist are effective to prevent solder bridges and to control amounts of solder on PC boards (As shown in Table 2).

	Recommended Application Examples	Examples of Solder Bridges
Narrow Spacing between Chip Components	<p>Solder Resist</p>	<p>Solder</p>
Radial Components are directly connected to Chip Components	<p>Solder Resist</p>	<p>Solder bridge</p>
Common lands are close to Chip Components	<p>Solder Resist</p>	<p>Solder bridge</p>

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Precautions for Assembly

Adhesives for Mounting

(1) Selection of adhesives

- The viscosity of an adhesive for mountings shall be such that the adhesive does not flow off on the land during its curing.
- If the adhesive is too low in its viscosity, mounted components may be out of alignment after or during soldering.
- The adhesives shall not be corrosive or chemically active to the mounted components and the PC boards.
- The amount of adhesive shall be such that the adhesive does not flow off or be out of alignment.
- Adhesives for mountings can be cured by ultraviolet or infrared radiation. In order to prevent the terminal electrodes of the Capacitors the curing shall be done at conditions of 180°C maximum, for 2 minutes maximum.

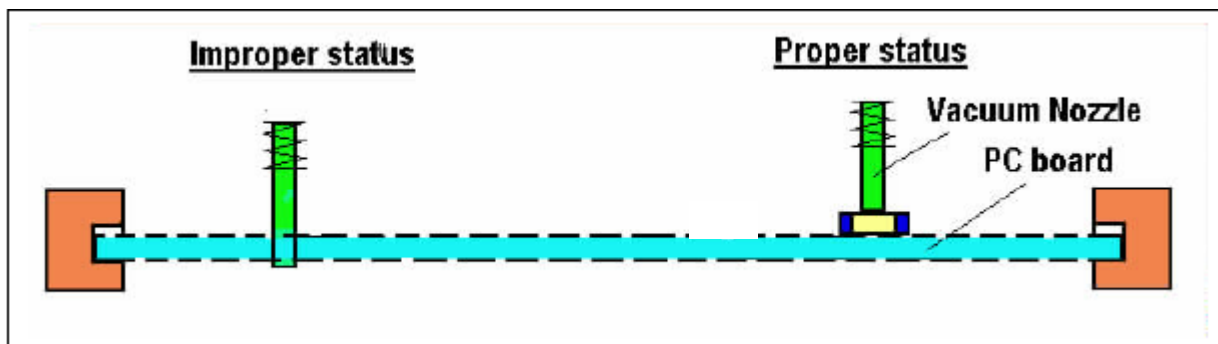
Chip Mounting consideration

In mounting the Capacitors / components on a printed circuit board, any bending and expanding force against them shall be kept minimum to prevent them from being damaged or cracked.

Following precautions and recommendation shall be observed carefully in the process:

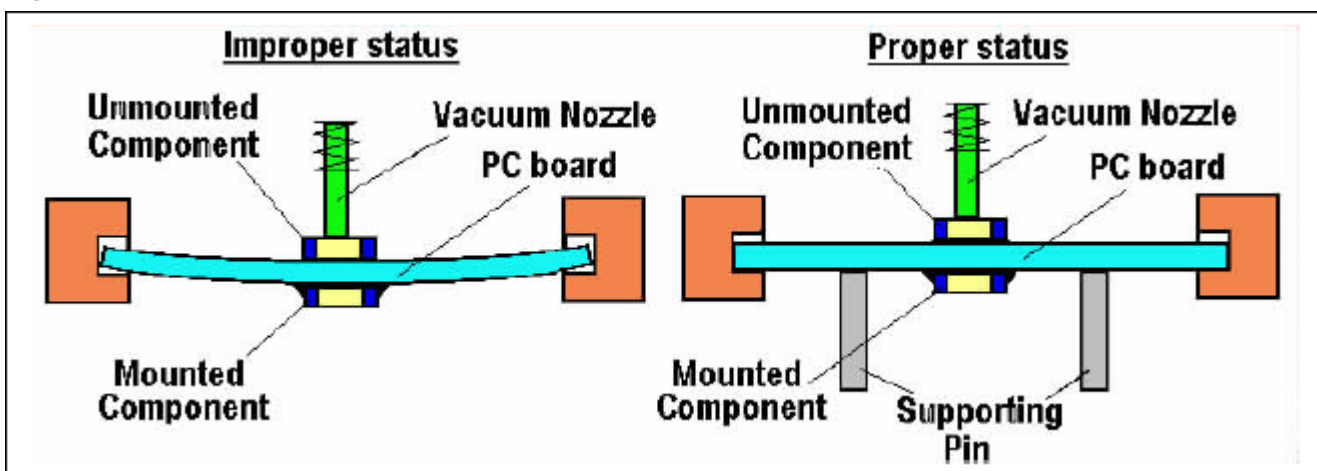
- Maximum stroke of the vacuum nozzle shall be adjusted so that the pushing force to the printed circuit board shall be limited to a static of 1 to 3 N (100 to 300 gf) (See Figure4).
- Maximum stroke of the nozzle shall be adjusted so that the maximum bending of printed circuit board does not exceed 0.5mm (See Figure 4)

Figure 4



(3) The printed circuit board shall be supported by means of adequate supporting pins as shown in Fig.5-(b)

Figure 5



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Soldering Flux and Solder

(1) Solder Flux:

- The content of halogen in the soldering shall be 0.2 wt% or less.
- Rosin-based and non-activated soldering flux is recommended.

(2) Water soluble type Soldering Flux:

In case of water soluble type soldering flux being applied, the flux residue on the surface of PC boards may have influences on the reliability of the components and cause deterioration and failures of them.

(3) Solder:

An eutectic solder (Sn63:Pb37) is recommended.

Soldering

Since a multilayer ceramic chip capacitor comes into direct contact with melted solder during soldering. It is exposed to potentially damaging mechanical stress caused by the sudden temperature change. The capacitor may also be subject to silver migration, and to contamination by the flux. Because of these factors, soldering technique is critical. Adhere to the following guidelines.

Hand soldering

In hand soldering of the Capacitors, large temperature gradient between preheated the capacitors and the tip of soldering iron may cause electrical failures and mechanical damages such as cracking of breaking of the devices. The soldering shall be carefully controlled and carried out so that the temperature gradient is kept minimum with following recommended conditions for hand soldering.

Recommended Soldering Conditions:

(1) Solder:

φ1mm Thread eutectic solder (Sn63:Pb37) with soldering flux *in the core.

*Rosin-based, and mom-activated flux is recommended.

(2) Preheating:

The capacitors shall be preheated so that "Temperature Gradient" between the devices and the tip of soldering iron is 150°C or below.

(3) Soldering iron:

Rated Power of 20W Max with 3mm soldering tip in diameter.

Temperature of soldering iron tip: 300°C maximum.

(The required amount of solder shall be melted in advance on the soldering tip.)

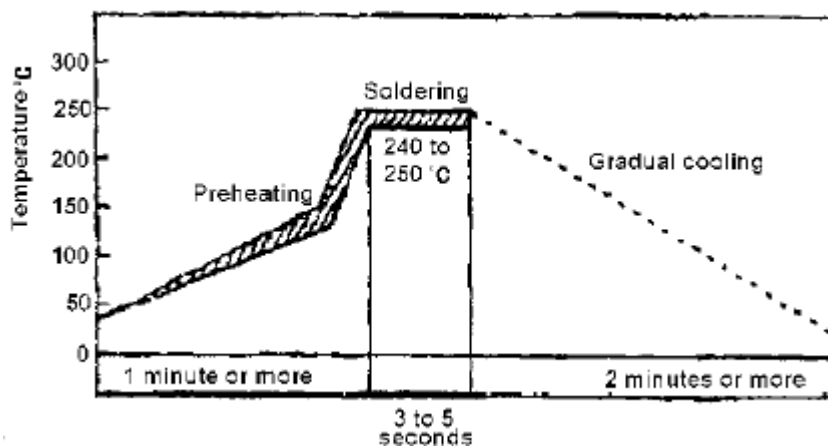
(4)Cooling:

After soldering, the Capacitors shall cooled gradually at room ambient temperature.

Flow Soldering

In flow soldering process, abnormal and thermal and mechanical stresses, caused by "Temperature Gradient" between the mounted Capacitors, resulting in failures and damages of the capacitors. So it is essential that the soldering process shall controlled to the following recommended conditions and precautions. (See Figure 6)

Figure 6 Recommended Soldering Temperature Time Profile (Flow soldering)



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(1) Application of Flux:

The soldering flux(3.3) shall applied to the mounted Capacitors thinly and uniformly by forming method.

(2) Preheating:

The mounted Capacitors / Components shall be preheated sufficiently so that the “ Temperature Gradient” between the Capacitors / Components and the melted solder shall be 150°C or below.

(3) Immersion to Soldering Bath:

The Capacitors shall be immersed into a soldering bath of 240 to 250°C for 3 to 5 seconds.

(4)Cooling:

The Capacitors shall be cooled gradually to room ambient temperature with the cooling temperature rates of 8°C/s maximum from 250°C to 170°C and 4°C/s maximum from 170°C to 130°C.

(5) Flux Cleaning:

When the Capacitors are immersed into cleaning solvent, it shall be confirmed that the surface temperature of devices do not exceed 100°C (See 3.5).

Reflow soldering.

In reflow soldering process, the mounted Capacitors / Components are generally heated and Soldering by a thermal conduction system such as an “Infrared radiation and hot blast soldering system” or a “Vapour Phase Soldering System (VPS)”, Large temperature gradients such as a rapid heating and cooling in the process may cause electrical and mechanical damages if the device. It is essential that the soldering process shall be controlled by following recommended conditions and precaution. (See Figure7)

For Tin-Lead (Sn/Pb) Termination component:

(1) Preheating 1.

The mounted Capacitors / Components shall be preheated sufficiently, for 60 to 90 seconds so that the surface temperature of them to be 140 to 150°C.

(2) Preheating 2.

After “Preheating 1”, the mounted Capacitors / Components shall be the elevated temperature of 150 to 200°C for 2 to 6 Seconds.

(3) Soldering:

The mounted Capacitors / Components shall be heated under the specified heating conditions (200 to 240 to 200°C for total 20 to 40 seconds, See Figure7) and shall be soldered at the maximum temperature of 240°C for 10 seconds of less.

(4)Cooling:

After the soldering, the mounted Capacitors / Components shall be gradually cooled to room ambient temperature for preventing mechanical damages such as cracking of the devices.

(5) Flux Cleaning:

When the mounted Capacitors / Components are immersed into cleaning solvent, it shall be confirmed the surfaces temperatures of them do not exceeding 100°C.

Note: If the mounted Capacitors / Components are partially heated in the soldering process, the devices may be separated form the printed circuit board by the surface tension of partially melted solder, and stand up like a “Tomb Stone”.

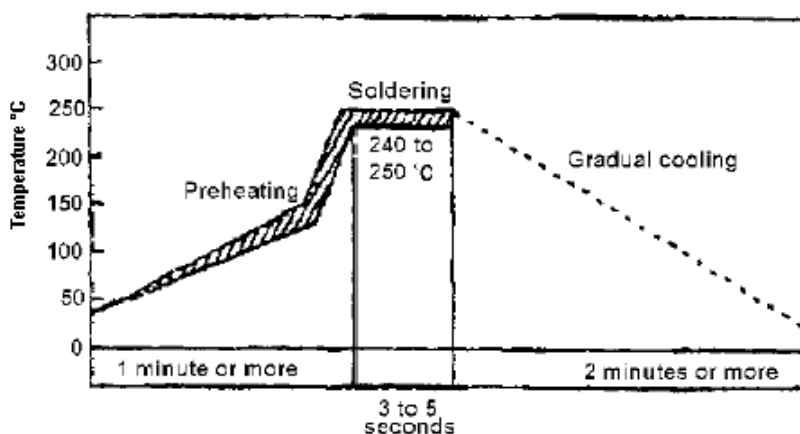


Figure 7 Recommended Soldering Temperature Time Profile for Tin-Lead component (Reflow Soldering)

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For Lead-free (Pure Tin plating termination) Termination component

Essentially, the soldering temperature for Lead-free component is a little higher than that for Tin-Lead component, but need to take consideration of the thermal effect for all other components mounting on board at the same time. The below picture is a recommended soldering profile for Lead-free component

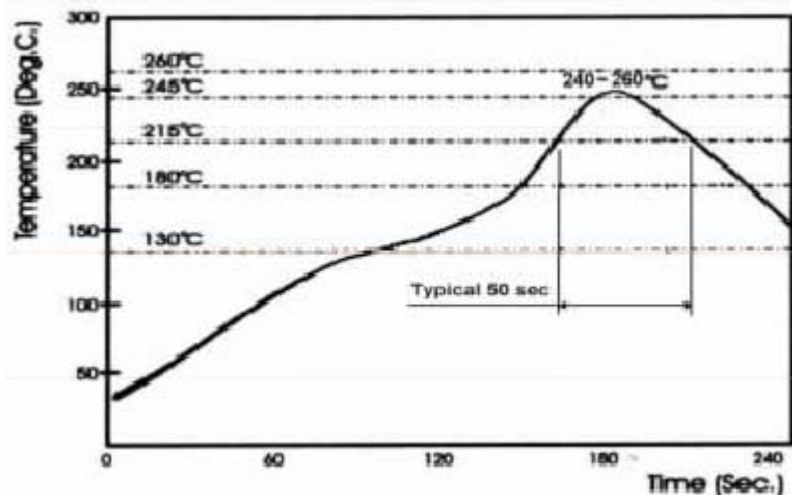


Figure 8 Recommended Soldering Temperature Time Profile for Lead-free component (Reflow Soldering)

Post soldering Cleaning

(1) Residues of corrosive soldering fluxes on the PC board after cleaning may greatly have influences on the electrical characteristics and the reliability, (such as humidity resistance) of the Capacitors, which have been mounted on the board. It shall be confirmed that the characteristic and reliability at the devices are not effected by applied cleaning conditions.

(2) Solubility of alternative cleaning solvent such as alcohol etc., is inferior to that of Freon cleaning solvent in the flux cleaning. So in case of alternative cleaning solvents, fresh cleaning solvent shall be used, and sufficient rinsing and drying shall be carried out.

(3) When an ultrasonic cleaning is applied to the mounted Capacitors on PC board, following conditions energy and the recommended for preventing failures or damages of the devices due to the large vibration energy and the resonant caused by the ultrasonic waves.

Frequency :29KHz maximum.

Radiated Power :20 W/litre maximum.

Period :5 minutes maximum.

Process Inspection

When the mounted printed circuit are inspected with measuring terminal pins, abnormal and excess mechanical stresses shall not be applied to the PC board mounted components, to prevent failure or damages of the devices.

(1) The mounted PC board shall be supported a same adequate supporting pins prevent their banding.

(2) It shall be confirmed that the measuring pin have the right tip in shape, equal in height and are set in the tight positions.

(3) The amount of adhesive shall be such that the adhesive dose flow off or be out of alignment.

Protective Coating

When the surface of a printed board on which the Capacitors has been mounted is coated with Resin to protect against moisture and dust, it shall be confirmed that the protective coat dose not have influences on reliability of the capacitors in the actual equipment.

(1) Coating materials, such as being corrosive and chemically active, shall not be applied to the capacitors and other components.

(2) Coating materials with a large expansively shall not be applied to the Capacitors for preventing failures or damages (such as cracking) of the devices in the curing process.

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Dividing / Breaking of PC Boards

- (1) Abnormal and excessive mechanical stresses, such as bending or expanding force on the components on the printed circuit board, shall be kept minimum in the dividing / breaking.
- (2) Dividing / Breaking of the PC board shall be done carefully at moderate speed using a Jig boards from mechanical damages.

Long Term Storage

The Capacitors shall not be stored under severe conditions of high temperatures and high humidity. Store them under 40°C maximum and 75%RH maximum Use them within 6 months and check the solderability before use.

Part Number Table

Type	Voltage (V)	Temperature Characteristics Code	Part Number	
0603	10	F	N0603F474ZCT	
			N0603F474ZNT	
	16	R	B0603R104KCT	
			B0603R104KNT	
	25	R	T0603R223KCT	
			T0603R473KCT	
			T0603R223KNT	
			T0603R473KNT	
			T0603F104ZCT	
			T0603F104ZNT	
	50	C	U0603C220JCT	
			U0603C101JCT	
			U0603C221JCT	
			U0603C102JCT	
			U0603C100JNT	
			U0603C220JNT	
			U0603C470JNT	
			U0603C101JNT	
			U0603C221JNT	
			U0603C331JNT	
			U0603C471JNT	
			U0603C102JNT	
			R	U0603R102KCT
				U0603R103KCT
				U0603R471KNT
				U0603R102KNT
				U0603R222KNT
				U0603R332KNT
	F	U0603R472KNT		
		U0603R103KNT		
			U0603F103ZNT	
			U0603F473ZNT	



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Part Number Table

Type	Voltage (V)	Temperature Characteristics Code	Part Number		
0805	10	R	N0805R105KCT		
			N0805R105KNT		
	16		B0805R224KCT		
			B0805R334KCT		
			B0805R474KCT		
			B0805R224KNT		
			B0805R334KNT		
			B0805R474KNT		
	25		F	T0805F105ZCT	
			T0805F105ZNT		
	50		C	U0805C102JCT	
				U0805C222JCT	
				U0805C102JNT	
				U0805C222JNT	
				R	U0805R102KCT
					U0805R103KCT
		U0805R223KCT			
		U0805R473KCT			
		U0805R104KCT			
		U0805R102KNT			
		U0805R222KNT			
		U0805R472KNT			
		U0805R103KNT			
		U0805R223KNT			
		U0805R473KNT			
		U0805R104KNT			
		F	U0805F104ZCT		
			U0805F104ZNT		
		100	C	A0805C100JCT	
				A0805C220JCT	
	A0805C330JCT				
	A0805C470JCT				
A0805C101JCT					
A0805C221JCT					
A0805C471JCT					
A0805C100JNT					
A0805C220JNT					
A0805C330JNT					



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Part Number Table

Type	Voltage (V)	Temperature Characteristics Code	Part Number		
0805	100	C	A0805C470JNT		
			A0805C101JNT		
			A0805C221JNT		
			A0805C331JNT		
			A0805C471JNT		
1206	10	R	N1206R225KCT		
			N1206R225KNT		
			B1206R105KCT		
	16	F	B1206F225ZCT		
			B1206F225ZNT		
			25	C	T1206C472JCT
					T1206C103JCT
	T1206C472JNT				
	T1206C103JNT				
	50	R	T1206R334KCT		
			T1206R474KCT		
			T1206R334KNT		
			T1206R474KNT		
			U1206R103KCT		
			U1206R104KCT		
			U1206R102KNT		
		U1206R222KNT			
		U1206R332KNT			
		U1206R472KNT			
		U1206R103KNT			
		U1206R223KNT			
		U1206R333KNT			
		U1206R473KNT			
	U1206R104KNT				
	F	B1206F475ZCT			
		B1206F475ZNT			
	100	C	A1206C100JCT		
A1206C220JCT					
A1206C101JCT					
A1206C221JCT					
A1206C331JCT					



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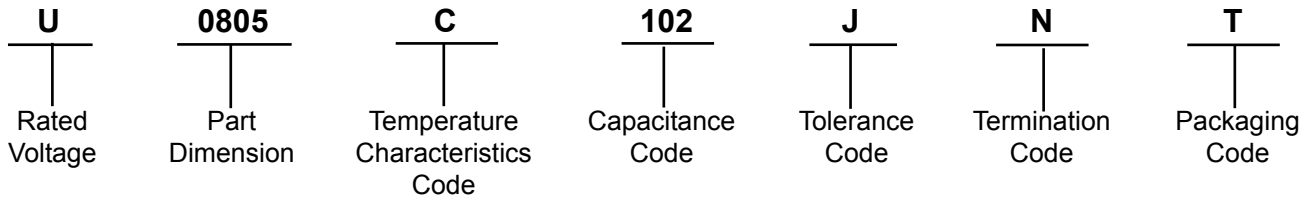
Multilayer Ceramic Capacitors



Part Number Table

Type	Voltage (V)	Temperature Characteristics Code	Part Number
1206	100	C	A1206C471JCT
			A1206C102JCT
			A1206C100JNT
			A1206C220JNT
			A1206C330JNT
			A1206C470JNT
			A1206C101JNT
			A1206C221JNT
			A1206C331JNT
			A1206C471JNT
			A1206C102JNT

Part Number Explanation



- Rated Voltage** : A, B, T and U.
- Part Dimension** : 0603, 0805 and 1206.
- Temperature Characteristics Code** : C, R and F.
- Capacitance Code** : 100, 101, 102, 103 and 472.
- Tolerance Code** : J, K and Z.
- Termination Code** : Termination Type.
- Packaging Code** : Packaging Type.